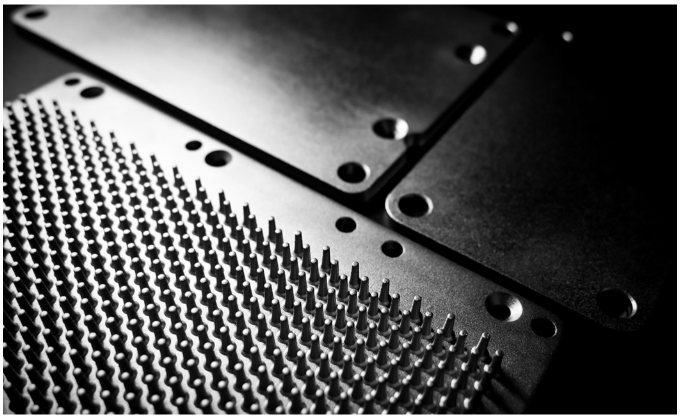
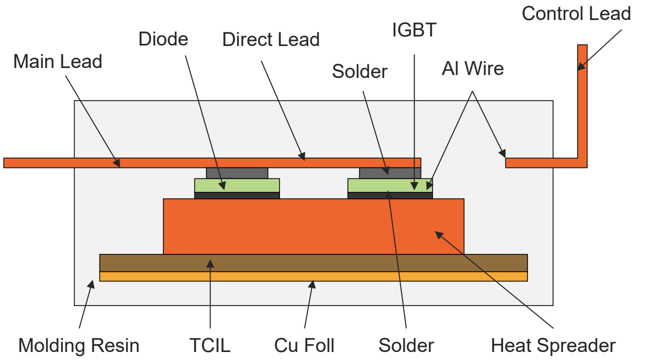


CMC AlSiC Heat Spreader

RoHS Compliant

General Description

Ceramic matrix compound to increase the thermal conductivity and the efficient heat dissipation at electronic components.



Could be replaced copper (Cu) or molybdenum copper (Mo-Cu)

Features

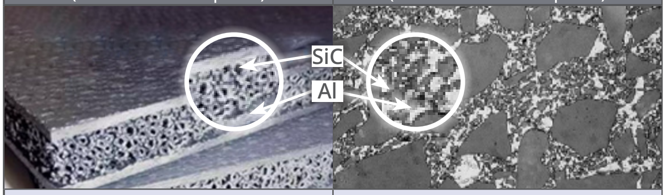
- Excellent stability under heating process
- No warpage after thermal cycling and solderability testing
- Low thermal expansion coefficient and High thermal conductivity
- Lower weight than Copper
- Lower thickness than Copper, and lower to 1mm
- Pass vibration resistance tests
- Higher life time than copper after thermal cycling

Specification

Properties	Unit	CMC AlSiC
Thermal Conductivity	W/m·K	150~180 (Based on different thickness)
Standard Product Dimensions L × W × H	mm	187x137x4.8
		140x99.5x4.65
		107x62x3.25
		39.5x39.5x1.6
Coefficient of Thermal Expansion, CTE	PPM/K	7~10
Strength	MPa	>300
Plating	µm	Ni --- 3
Density	g/cm^3	2.6~3.0

※ Product dimensions can be customized.
※ All products undergo surface nickel plating in accordance with specifications prior to shipment.

CMC AlSiC and MMC Comparison:



MMC (Metal Matrix Composite)	CMC (Ceramic Matrix Composite)
Al bond SiC on surface only	Al bond SiC everywhere

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